

East 8 WPID, JPO

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	261047	pore or porous or foraminous	JPO; DERWENT	OR	ON	2006/01/12 21:26
L2	1141234	laminat\$ or bond\$ or fuse or fusing or fused	JPO; DERWENT	OR	ON	2006/01/12 21:22
L3	17985	1 with 2	JPO; DERWENT	OR	ON	2006/01/12 21:22
L4	2706744	semiconduct\$ or wafer or chip or silicon or gallium or gaas or si or gainas	JPO; DERWENT	OR	ON	2006/01/12 21:23
L5	2640	3 and 4	JPO; DERWENT	OR	ON	2006/01/12 21:23
L6	3010393	etch\$ or patern\$ or peel\$ or separat\$ or remov\$ or delaminat\$	JPO; DERWENT	OR	ON	2006/01/12 21:24
L7	765	5 and 6	JPO; DERWENT	OR	ON	2006/01/12 21:24
L8	34747	1 with 6	JPO; DERWENT	OR	ON	2006/01/12 21:25
L9	481	7 and 8	JPO; DERWENT	OR	ON	2006/01/12 21:26
L10	261047	1 with 1	JPO; DERWENT	OR	ON	2006/01/12 21:26
L11	17985	1 with 2 with 1	JPO; DERWENT	OR	ON	2006/01/12 21:26
L12	261047	(pore or porous or foraminous) with (pore or porous or foraminous)	JPO; DERWENT	OR	ON	2006/01/12 21:27
L13	2153	1 with 2 with 6	JPO; DERWENT	OR	ON	2006/01/12 21:28
L14	361	9 and 13	JPO; DERWENT	OR	ON	2006/01/12 21:32
L15	261047	1 with (1st or first or 1 st)	JPO; DERWENT	OR	ON	2006/01/12 21:33
L16	26143	1 with (2nd or 2 nd or second)	JPO; DERWENT	OR	ON	2006/01/12 21:33
L17	9042	1 with (2nd or "2 nd" or second)	JPO; DERWENT	OR	ON	2006/01/12 21:33
L18	9891	1 with (1st or first or "1 st")	JPO; DERWENT	OR	ON	2006/01/12 21:33
L19	641	17 and 18 and 4 and 6	JPO; DERWENT	OR	ON	2006/01/12 21:33
L20	34747	1 with 6	JPO; DERWENT	OR	ON	2006/01/12 21:33
L21	457	19 and 20	JPO; DERWENT	OR	ON	2006/01/12 21:34

L22	96	21 and 2	JPO; DERWENT	OR	ON	2006/01/12 21:43
L23	361	21 not 22	JPO; DERWENT	OR	ON	2006/01/12 21:43
L24	38	23 and (base or soi)	JPO; DERWENT	OR	ON	2006/01/12 21:45
L25	323	23 not 24	JPO; DERWENT	OR	ON	2006/01/12 21:45
L26	115	25 and substrate	JPO; DERWENT	OR	ON	2006/01/12 21:45

East 8 WPIJ JPO

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	79179	peel\$ or delaminat\$ or "de laminat\$"	DERWENT	OR	ON	2006/01/12 18:17
L2	339534	void or cavity or cavities or indent\$ or pocket	DERWENT	OR	ON	2006/01/12 18:17
L3	875920	semiconduct\$ or wafer or chip or epi\$	DERWENT	OR	ON	2006/01/12 18:18
L4	241	1 and 2 and 3	DERWENT	OR	ON	2006/01/12 18:18
L5	1133045	dielectric or insulat\$ or sio or sio2 or \$glass\$ or \$silicat\$	DERWENT	OR	ON	2006/01/12 18:19
L6	83	4 and 5	DERWENT	OR	ON	2006/01/12 18:19
L7	619	1 with 2	DERWENT	OR	ON	2006/01/12 18:19
L8	101	4 and 7	DERWENT	OR	ON	2006/01/12 18:19
L9	35	6 and 8	DERWENT	OR	ON	2006/01/12 18:23
L10	66	8 not 9	DERWENT	OR	ON	2006/01/12 18:30
L11	48	6 not 8	DERWENT	OR	ON	2006/01/12 18:35
L12	1301814	separat\$ or releas\$	DERWENT	OR	ON	2006/01/12 18:35
L13	2097	2 and 3 and 12	DERWENT	OR	ON	2006/01/12 18:35
L14	542	13 and 5	DERWENT	OR	ON	2006/01/12 18:35
L15	18973	12 with 2	DERWENT	OR	ON	2006/01/12 18:35
L16	205	14 and 15	DERWENT	OR	ON	2006/01/12 18:35
L17	200	16 not (8 or 6)	DERWENT	OR	ON	2006/01/12 18:57
L18	1003132	bond\$ or laminat\$	JPO; DERWENT	OR	ON	2006/01/12 18:58
L19	52347	void	JPO; DERWENT	OR	ON	2006/01/12 18:58
L20	3472	18 with 19	JPO; DERWENT	OR	ON	2006/01/12 18:58
L21	339	3 and 20	JPO; DERWENT	OR	ON	2006/01/12 18:58
L22	110	5 and 21	JPO; DERWENT	OR	ON	2006/01/12 18:58
L23	321	21 not (6 or 8 or 17)	JPO; DERWENT	OR	ON	2006/01/12 19:02

STN 8 Cas, Japio

(FILE 'HOME' ENTERED AT 16:09:12 ON 12 JAN 2006)

FILE 'CAPLUS' ENTERED AT 16:09:20 ON 12 JAN 2006

L1 70045 S PEEL? OR DELAMINAT? OR DE(W)LAMINAT?
L2 237730 S VOID? OR CAVIT? OR INDENT? OR POCKET?
L3 1398 S L1 AND L2
L4 1374974 S SEMICONDUCT? OR WAFER? OR CHIP? OR EPI?
L5 183 S L3 AND L4
L6 1543013 S ETCH? OR PATTERN? OR REMOV? OR ?POLISH? OR CHEMIMECH? OR LAP?
L7 30 S L5 AND L6
L8 102 S L5 AND (CMP OR PLANARIZ? OR PREETCH? OR POSTETCH? OR BASE? OR
L9 112 S L7 OR L8
L10 71 S L5 NOT L9

FILE 'JAPIO' ENTERED AT 16:13:49 ON 12 JAN 2006

L11 79 S L8
L12 95 S L9
L13 55 S L10